

**METHOD FOR OPERATING CHEMICAL MECHANICAL
POLISHING (“CMP”) TOOL FOR THE MANUFACTURE OF
SEMICONDUCTOR DEVICES**

ABSTRACT OF THE DISCLOSURE

A method for processing integrated circuit devices including a water recycling process. The method includes operating a chemical mechanical planarization process, which includes a discharge for process water. The process water is used to process one or more semiconductor wafers. The method also selectively discharges process water from the discharge. A step of transferring the process water from the chemical mechanical planarization process to a facility process is included. The method then uses the discharged water in the facility process.

PA 3237673 v1